

DS26S10

DS26S10 Quad Bus Transceiver



Literature Number: SNOSBL4

DS26S10 Quad Bus Transceiver

General Description

The DS26S10 is a quad Bus Transceiver consisting of 4 high speed bus drivers with open-collector outputs capable of sinking 100 mA at 0.8V and 4 high speed bus receivers. Each driver output is connected internally to the high speed bus receiver in addition to being connected to the package pin. The receiver has a Schottky TTL output capable of driving 10 Schottky TTL unit loads.

An active low enable gate controls the 4 drivers so that outputs of different device drivers can be connected together for party-line operation.

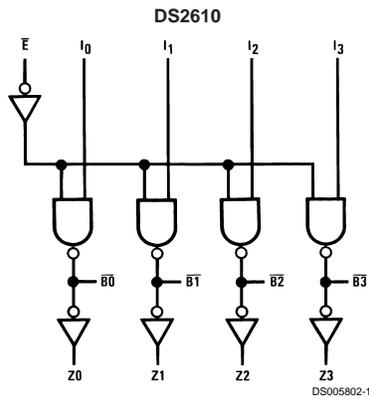
The bus output high-drive capability in the low state allows party-line operation with a line impedance as low as 100Ω. The line can be terminated at both ends, and still give considerable noise margin at the receiver. The receiver typical switching point is 2V.

The DS26S10 features advanced Schottky processing to minimize propagation delay. The device package also has 2 ground pins to improve ground current handling and allow close decoupling between V_{CC} and ground at the package. Both GND 1 and GND 2 should be tied to the ground bus external to the device package.

Features

- Input to bus is inverting on DS26S10
- Quad high speed open-collector bus transceivers
- Driver outputs can sink 100 mA at 0.8V maximum
- Advanced Schottky processing
- PNP inputs to reduce input loading

Logic Diagrams



Absolute Maximum Ratings (Note *NO

TARGET FOR FNXref NS859*)

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/ Distributors for availability and specifications.

Storage Temperature	-65°C to +150°C
Temperature (Ambient) Under Bias	-55°C to +125°C
Supply Voltage to Ground Potential	-0.5V to +7V
DC Voltage Applied to Outputs for High Output State	-0.5V to +V _{CC} Max
DC Input Voltage	-0.5V to +5.5V
Output Current, Into Bus	200 mA
Output Current, Into Outputs (Except Bus)	30 mA

DC Input Current	-30 mA to +5 mA
Maximum Power Dissipation (Note 1) at 25°C	
Molded Package	1362 mW

Operating Conditions

	Min	Max	Units
Supply Voltage (V _{CC})			
DS26S10	4.75	5.25	V
Temperature (T _A)			
DS26S10	0	+70	°C

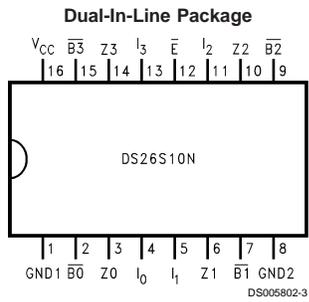
Note 1: Derate cavity package 9.6 mW/°C above 25°C; derate molded package 10.9 mW/°C above 25°C, derate PLCC package TBD mW/°C above 25°C.

Electrical Characteristics

(Unless otherwise noted)

Symbol	Parameter	Conditions		Min	Typ (Note 3)	Max	Units
		(Note 2)					
V _{OH}	Output High Voltage (Receiver Outputs)	V _{CC} = Min, I _{OH} = -1 mA,	Military	2.5	3.4		V
		V _{IN} = V _{IL} or V _{IH}	Commercial	2.7	3.4		V
V _{OL}	Output Low Voltage (Receiver Outputs)	V _{CC} = Min, I _{OL} = 20 mA, V _{IN} = V _{IL} or V _{IH}				0.5	V
V _{IH}	Input High Level (Except Bus)	Guaranteed Input Logical High for All Inputs		2.0			V
V _{IL}	Input Low Level (Except Bus)	Guaranteed Input Logical Low for All Inputs				0.8	V
V _I	Input Clamp Voltage (Except Bus)	V _{CC} = Min, I _{IN} = -18 mA				-1.2	V
I _{IL}	Input Low Current (Except Bus)	V _{CC} = Max, V _{IN} = 0.4V	Enable			-0.36	mA
			Data			-0.54	mA
I _{IH}	Input High Current (Except Bus)	V _{CC} = Max, V _{IN} = 2.7V	Enable			20	µA
			Data			30	µA
I _I	Input High Current (Except Bus)	V _{CC} = Max, V _{IN} = 5.5V				100	µA
I _{SC}	Output Short-Circuit Current (Except Bus)	V _{CC} = Max, (Note 4)	Military	-20		-55	mA
			Commercial	-18		-60	mA
I _{CCL}	Power Supply Current (All Bus Outputs Low)	V _{CC} = Max, Enable = GND	DS26S10		45	70	mA
			DS26S11			80	mA

Connection Diagram



Top View
Order Number DS26S10N
See NS Package Number N16A
Plastic Chip Carrier

Bus Input/Output Characteristics

Symbol	Parameter	Conditions (Note 2)	Min	Typ(Note 3)	Max	Units	
V_{OL}	Output Low Voltage	$V_{CC} = \text{Min}$	$I_{OL} = 40 \text{ mA}$		0.33	0.5	V
			$I_{OL} = 70 \text{ mA}$		0.42	0.05	
			$I_{OL} = 100 \text{ mA}$		0.51	0.8	
I_O	Bus Leakage Current	$V_{CC} = \text{Max}$	$V_O = 0.8\text{V}$			-50	μA
			$V_O = 4.5\text{V}$			100	
I_{OFF}	Bus Leakage Current (power OFF)	$V_O = 4.5\text{V}$			100	μA	
V_{TH}	Receiver Input High Threshold	Bus enable = 2.4V $V_{CC} = \text{Max}$	2.25	2.0		V	
V_{TL}	Receiver Input Low Threshold	Bus enable = 2.4V $V_{CC} = \text{Min}$		2.0	1.75		

Note 2: For conditions shown as min or max, use the appropriate value specified under Electrical Characteristics for the applicable device type.

Note 3: Typical limits are at $V_{CC} = 5\text{V}$, 25°C ambient and maximum loading.

Note 4: Not more than one output should be shorted at a time. Duration of the short circuit test should not exceed one second.

Switching Characteristics

($T_A = 25^\circ\text{C}$, $V_{CC} = 5\text{V}$)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
t_{PLH}	Data Input to Bus	$R_B = 50\Omega$, $C_B = 50 \text{ pF}$ (Note 5)		10	15	ns
t_{PHL}	Data Input to Bus					
t_{PLH}	Enable Input to Bus	$R_B = 50\Omega$, $C_B = 50 \text{ pF}$ (Note 5)		14	18	ns
t_{PHL}	Enable Input to Bus					
t_{PLH}	Bus to Receiver Out	$R_B = 50\Omega$, $R_L = 280\Omega$, $C_B = 50 \text{ pF}$ (Note 5) $C_L = 15 \text{ pF}$		10	15	ns
t_{PHL}	Bus to Receiver Out					
t_r	Bus	$R_B = 50\Omega$, $C_B = 50 \text{ pF}$ (Note 5)	4.0	10		ns
t_f	Bus					

Note 5: Includes probe and jig capacitance.

Truth Tables

DS26S10

Inputs		Outputs	
\bar{E}	I	\bar{B}	Z
L	L	H	L
L	H	L	H
H	X	Y	\bar{Y}

H = High voltage level

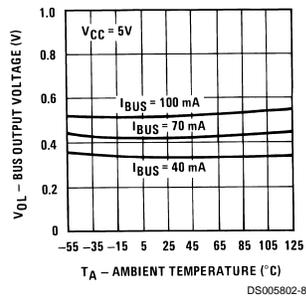
L = Low voltage level

X = Don't care

Y = Voltage level of bus (assumes control by another bus transceiver)

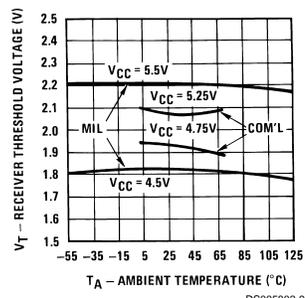
Typical Performance Characteristics

Typical Bus Output Low Voltage vs Ambient Temperature



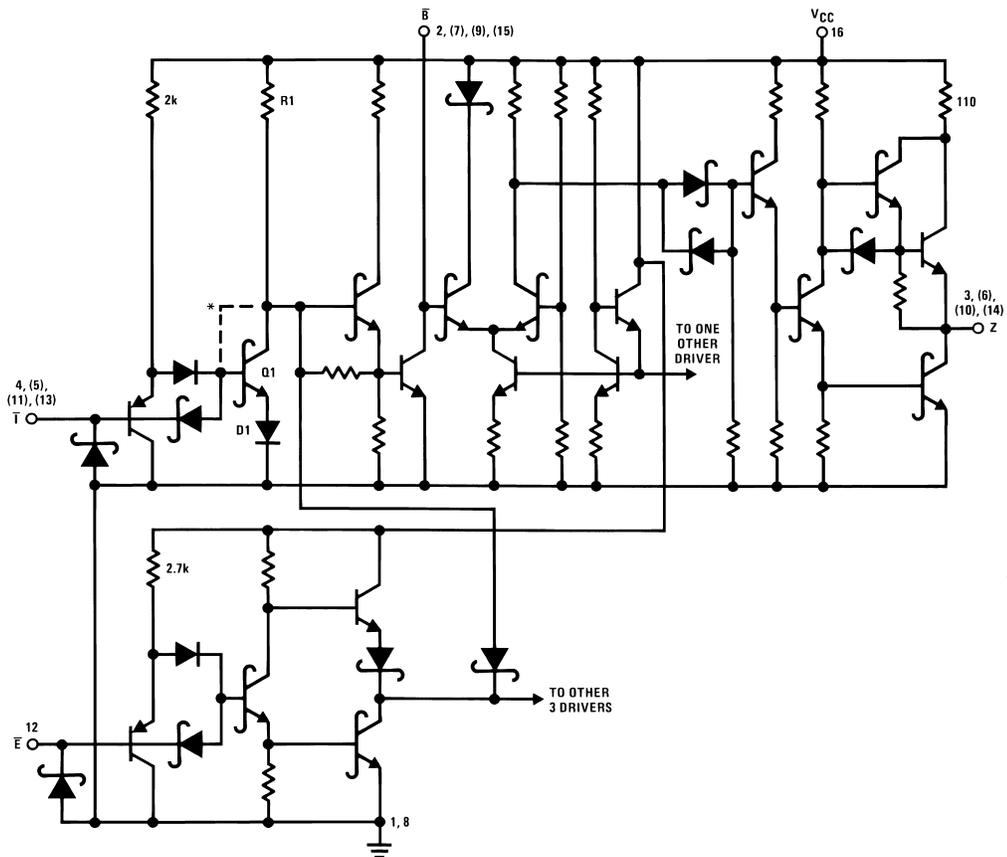
DS005802-8

Receiver Threshold Variation vs Ambient Temperature



DS005802-9

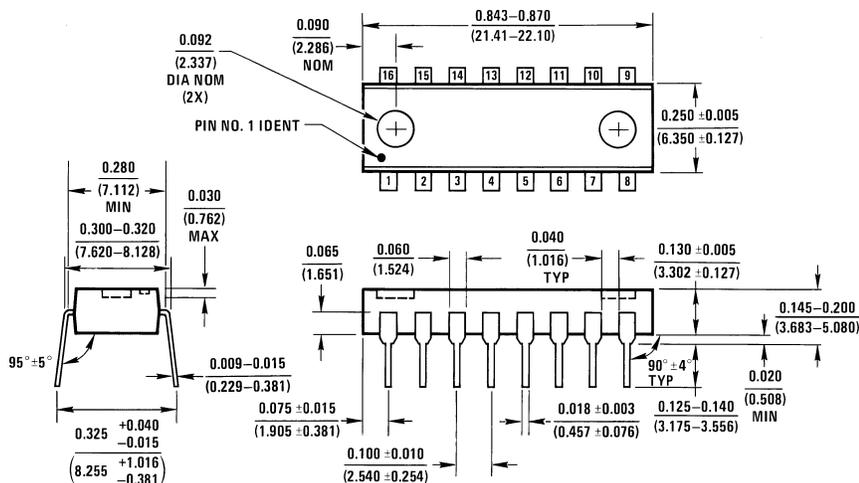
Schematic Diagram



DS005802-10

VCC = Pin 16
 GND 1 = Pin 1
 GND 2 = Pin 8
 Connect for DS26S10
 *Remove R1, Q1, D1 for DS26S10

Physical Dimensions inches (millimeters) unless otherwise noted



Molded Dual-In-Line Package (N)
Order Number DS26S10N
NS Package Number N16A

N16A (REV E)

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